

Title (en)

Method for producing matt copper deposits

Title (de)

Verfahren zur Herstellung von matten Kupferablagerungen

Title (fr)

Procédé de production de dépôts de cuivre mate

Publication

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Application

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Priority

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Abstract (en)

[origin: EP2620529A1] The present invention relates to a method for deposition of a matt copper coating wherein a first copper layer is deposited from an aqueous copper electrolyte which does not contain an organic compound comprising divalent sulfur. A second copper layer is then deposited onto the first copper layer from an aqueous copper electrolyte comprising a first and a second water soluble sulfur-containing additive wherein the first water soluble sulfur-containing compound is an alkyl sulfonic acid derivative and the second water soluble sulfur-containing additive is an aromatic sulfonic acid derivative. The method provides copper layers with a homogeneous and adjustable matt appearance for decorative applications.

IPC 8 full level

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